

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

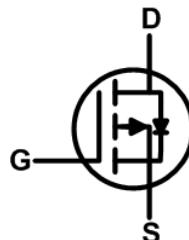
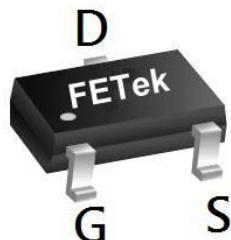
**Product Summary**


BVDSS	RDS(ON)	ID
-20V	100mΩ	-3.3A

**Description**

The FKUC2301 is the high cell density trenched P-ch MOSFETs, which provides excellent RDS(ON) and efficiency for most of the small power switching and load switch applications.

The FKUC2301 meet the RoHS and Green Product requirement with full function reliability approved.

**SOT23S Pin Configuration**

**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-20	V
V <sub>GS</sub>	Gate-Source Voltage	±12	V
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sup>1</sup>	-3.3	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sup>1</sup>	-2.6	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	-13	A
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>3</sup>	1.4	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-ambient <sup>1</sup>	---	125	°C/W
R <sub>θJA</sub>	Thermal Resistance Junction-ambient <sup>1</sup> (t≤10s)	---	90	°C/W

### Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=-250\mu\text{A}$	-20	---	---	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-4.5\text{V}$ , $I_D=-3\text{A}$	---	76	100	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}$ , $I_D=-2\text{A}$	---	110	135	
		$V_{\text{GS}}=-1.8\text{V}$ , $I_D=-0.9\text{A}$	---	160	240	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=-250\mu\text{A}$	-0.45	-0.6	-1.0	V
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-16\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-1	$\text{uA}$
		$V_{\text{DS}}=-16\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	-5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 12\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=-5\text{V}$ , $I_D=-3\text{A}$	---	12.2	---	S
$Q_g$	Total Gate Charge (-4.5V)	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=-4.5\text{V}$ , $I_D=-3\text{A}$	---	10.1	---	$\text{nC}$
$Q_{\text{gs}}$	Gate-Source Charge		---	1.21	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	2.46	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=-10\text{V}$ , $V_{\text{GS}}=-4.5\text{V}$ , $R_G=3.3\Omega$	---	5.6	---	$\text{ns}$
$T_r$	Rise Time		---	32.2	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	45.6	---	
$T_f$	Fall Time		---	29.2	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	677	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	82	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	73	---	

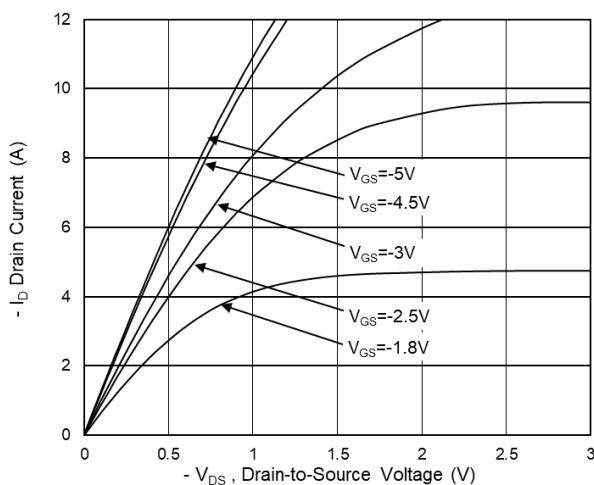
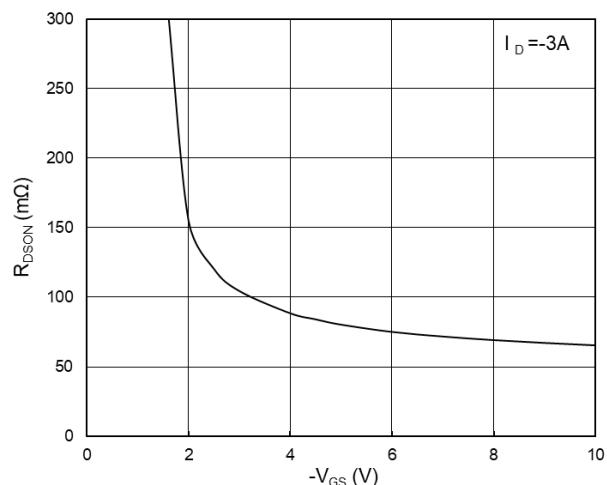
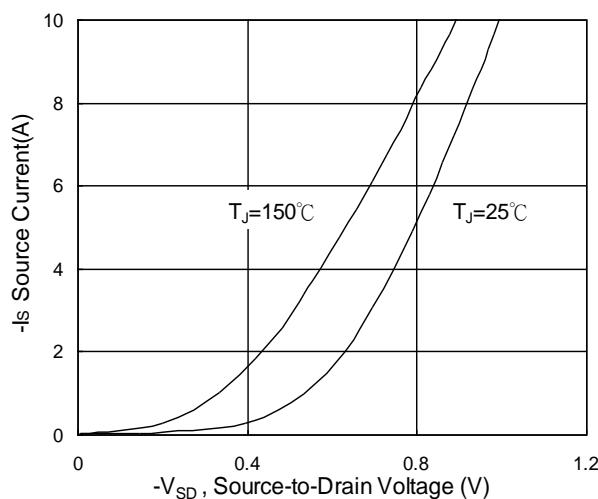
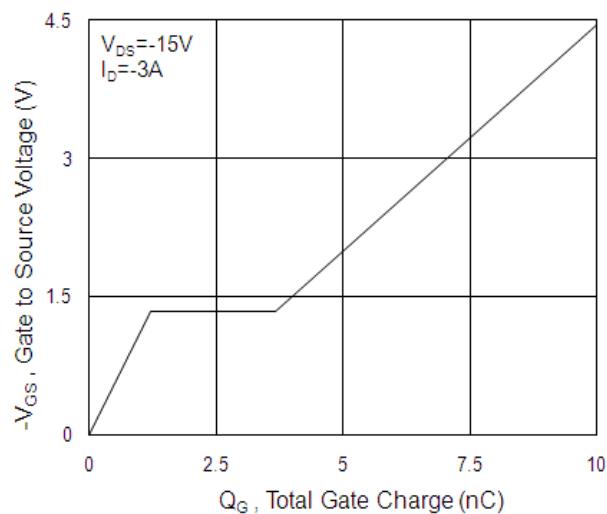
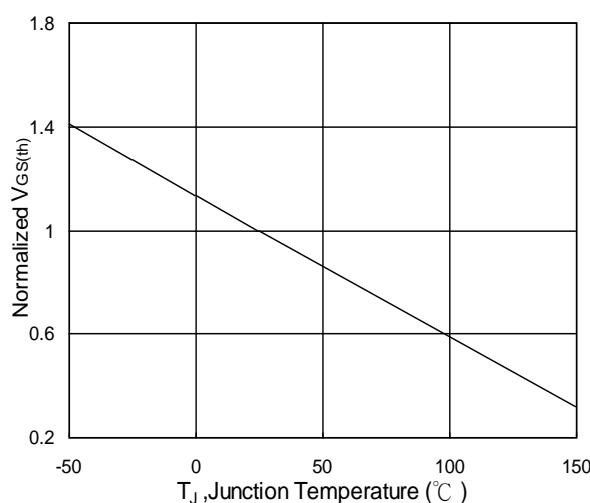
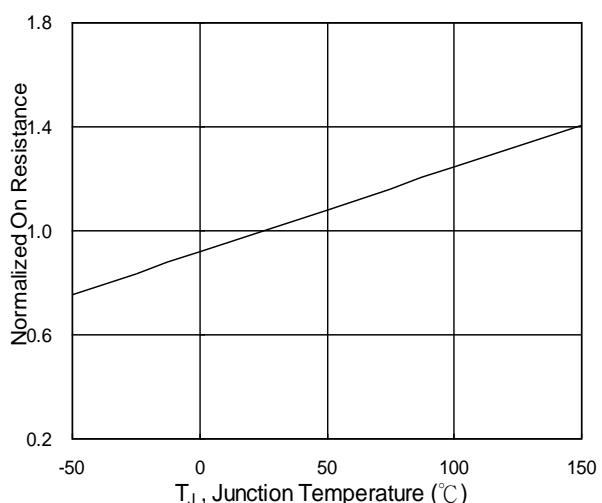
### Diode Characteristics

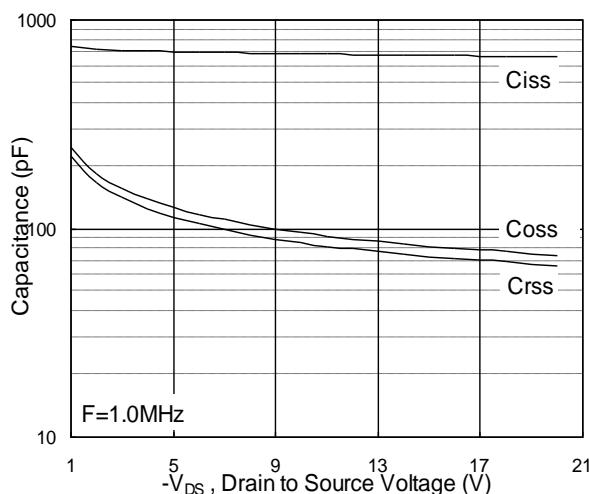
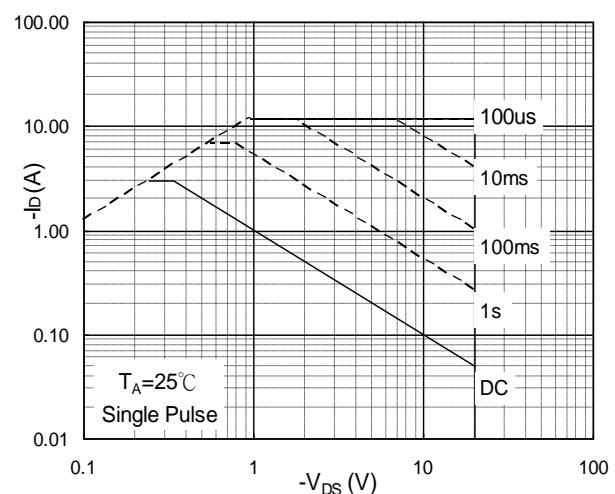
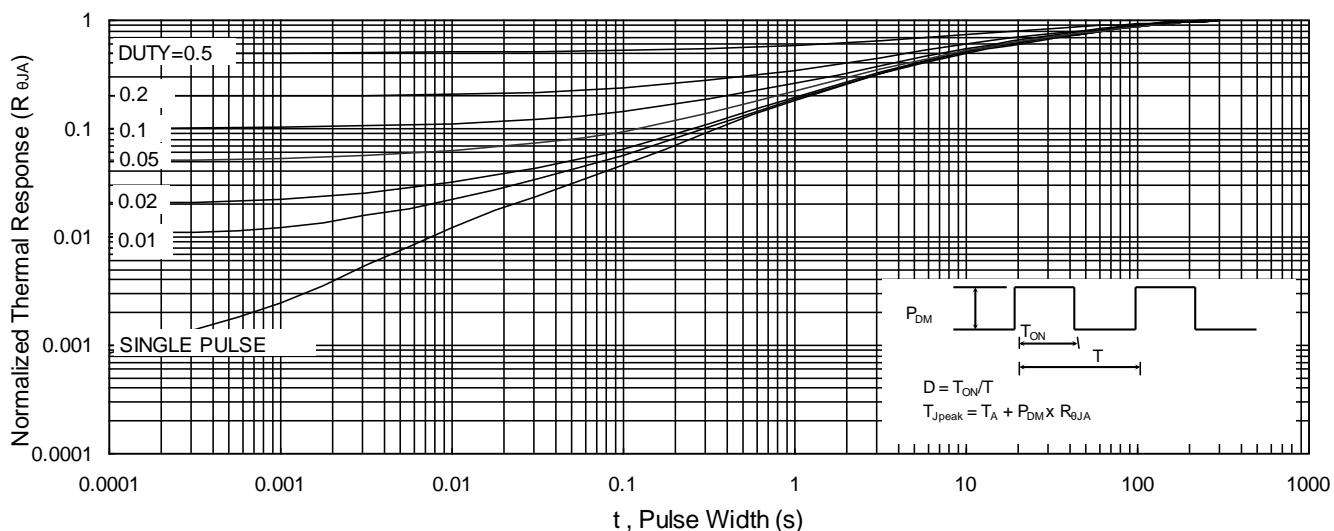
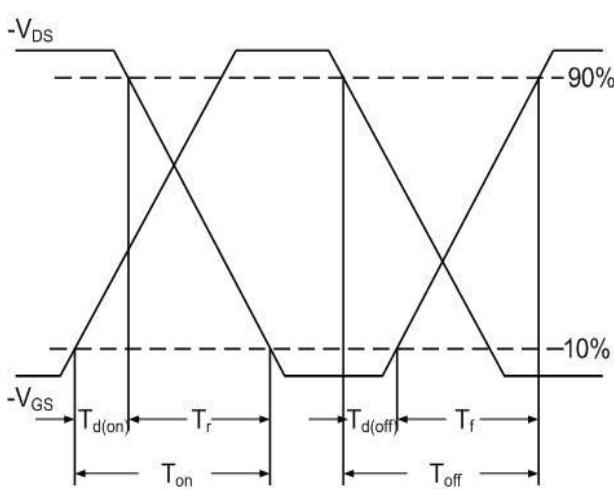
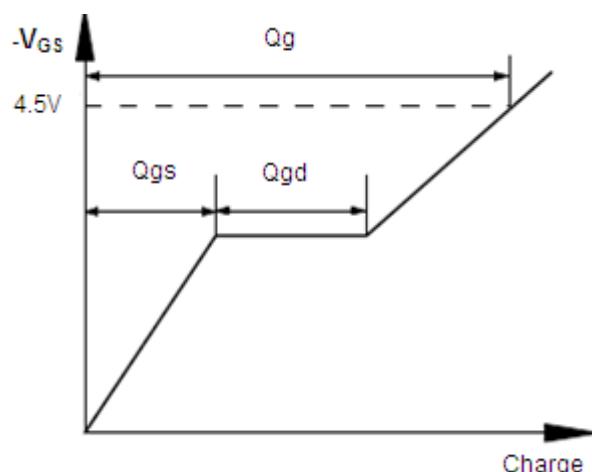
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,4</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	-3	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1	V

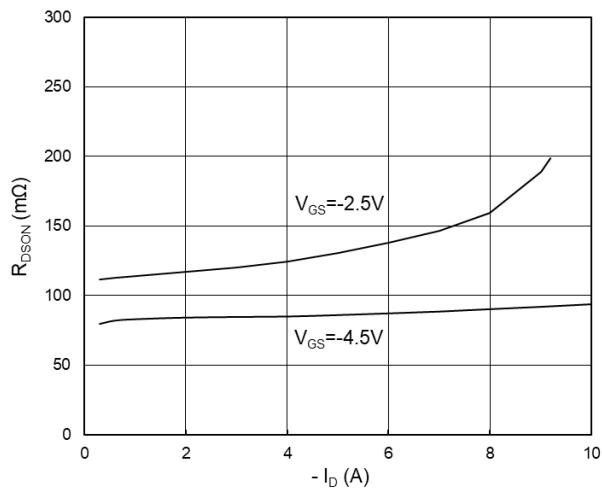
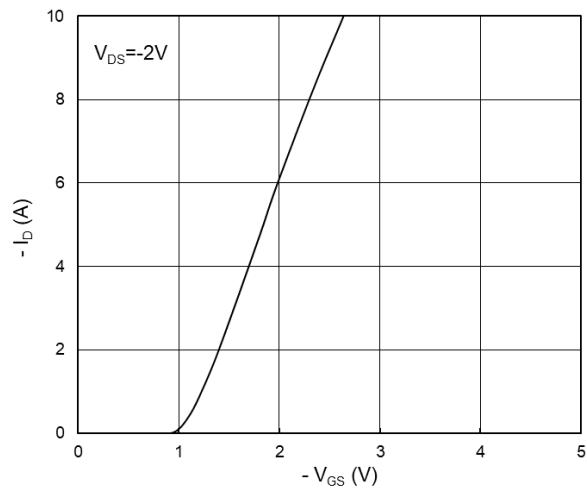
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 4.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

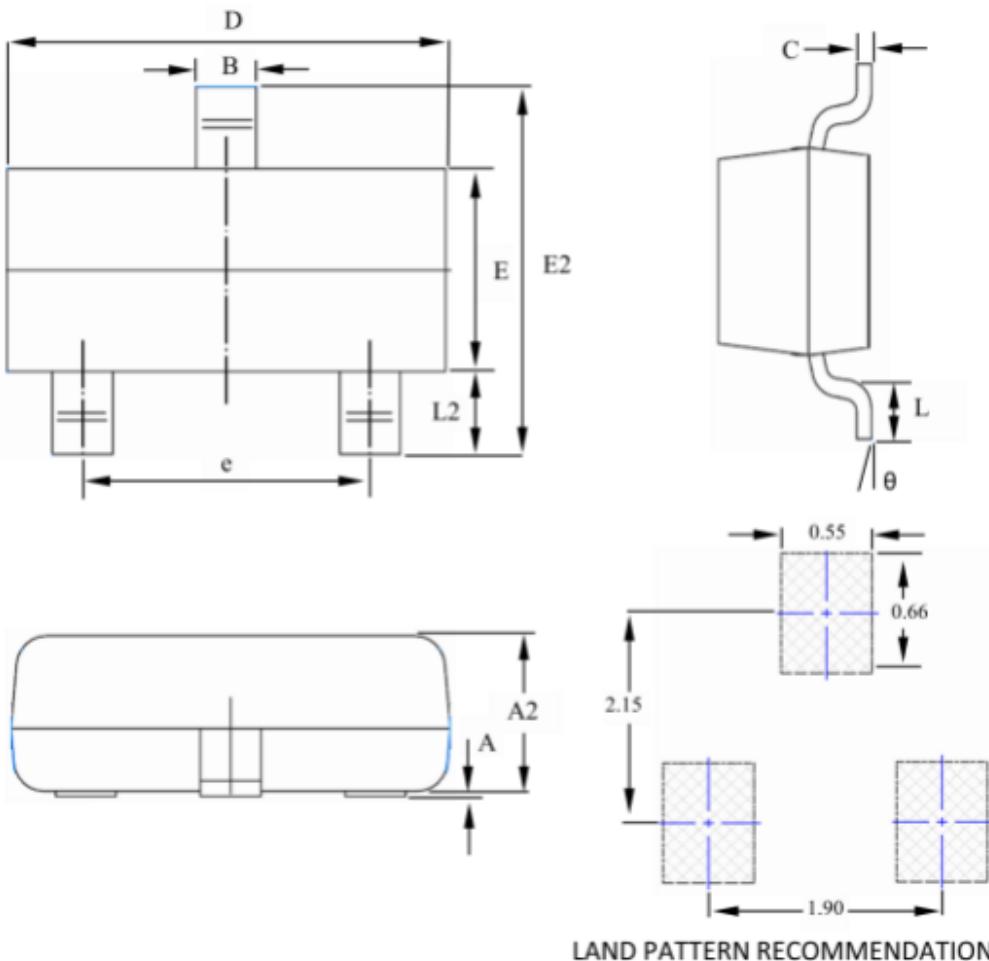
### Typical Characteristics


**Fig.1 Typical Output Characteristics**

**Fig.2 On-Resistance vs G-S Voltage**

**Fig.3 Source Drain Forward Characteristics**

**Fig.4 Gate-Charge Characteristics**

**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$** 

**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**


**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Gate Charge Waveform**


**Fig.12 On-Resistance vs. Drain Current**

**Fig.13 Transfer Characteristics**

## SOT23S Package Outline Dimensions


**LAND PATTERN RECOMMENDATION**

SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.00	--	0.10	0.000	--	0.004
A2	0.90	--	1.10	0.035	--	0.041
B	0.30	--	0.50	0.012	--	0.020
C	0.08	--	0.15	0.003	--	0.006
D	2.80	--	3.00	0.110	--	0.118
E	1.20	--	1.40	0.047	--	0.055
E2	2.25	--	2.55	0.089	--	0.100
L	0.30	--	0.50	0.012	--	0.020
L2	0.50	--	0.60	0.020	--	0.024
θ	0°	--	8°	0°	--	8°
e	1.80	--	2.00	0.071	--	0.079